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Mechanical standardization of semiconductor devices –

Part 6:
General rules for the preparation of outline drawings of surface mounted semiconductor device packages

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages

FOREWORD

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International Standard IEC 60191-6 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

This second edition of IEC 60191-6 cancels and replaces the first edition, published in 1990 and its amendment 1 (1999), and constitutes a technical revision. This includes the following significant changes with respect to the previous edition: improvement of the geometrical drawing format and addition of the examples of the drawing of major packages.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/584/FDIS	47D/587/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages

1 Scope

This part of IEC 60191 gives general rules for the preparation of outlines drawings of surface-mounted semiconductor devices. It supplements IEC 60191-1 and 60191-3. It covers all surface-mounted devices-discrete semiconductors as well as integrated circuits classified as form E in Clause 3 of IEC 60191-4.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-1:1966, *Mechanical standardization of semiconductor devices – Part 1: Preparation of drawings of semiconductor devices*

IEC 60191-3:1999, *Mechanical standardization of semiconductor devices – Part 3: General rules for the preparation of outline drawings of integrated circuits*

IEC 60191-4:1999, *Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor devices*

ISO 1101:1983, *Technical drawings – Geometrical tolerancing – Tolerancing of form, orientation, location and run-out – Generalities, definitions, symbols, indications on drawings*